

# 1300nm Optics for Short Reach SMF Application

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# Introduction

- At the Chicago, 2011 meeting of the Next Gen 100GbE Optical SG, alternative Single Mode technology was identified as a key area to be addressed.
- This contribution explores technical feasibility of 4ch x 25G 1310nm optical device technology for short reach SMF (< 2 km) and extended reach MMF (< 300m) applications.
- Characteristics of transceiver power consumption, module form factor and relative cost are analyzed.

# Focus of Proposal for 4ch x 25G Optical Interface

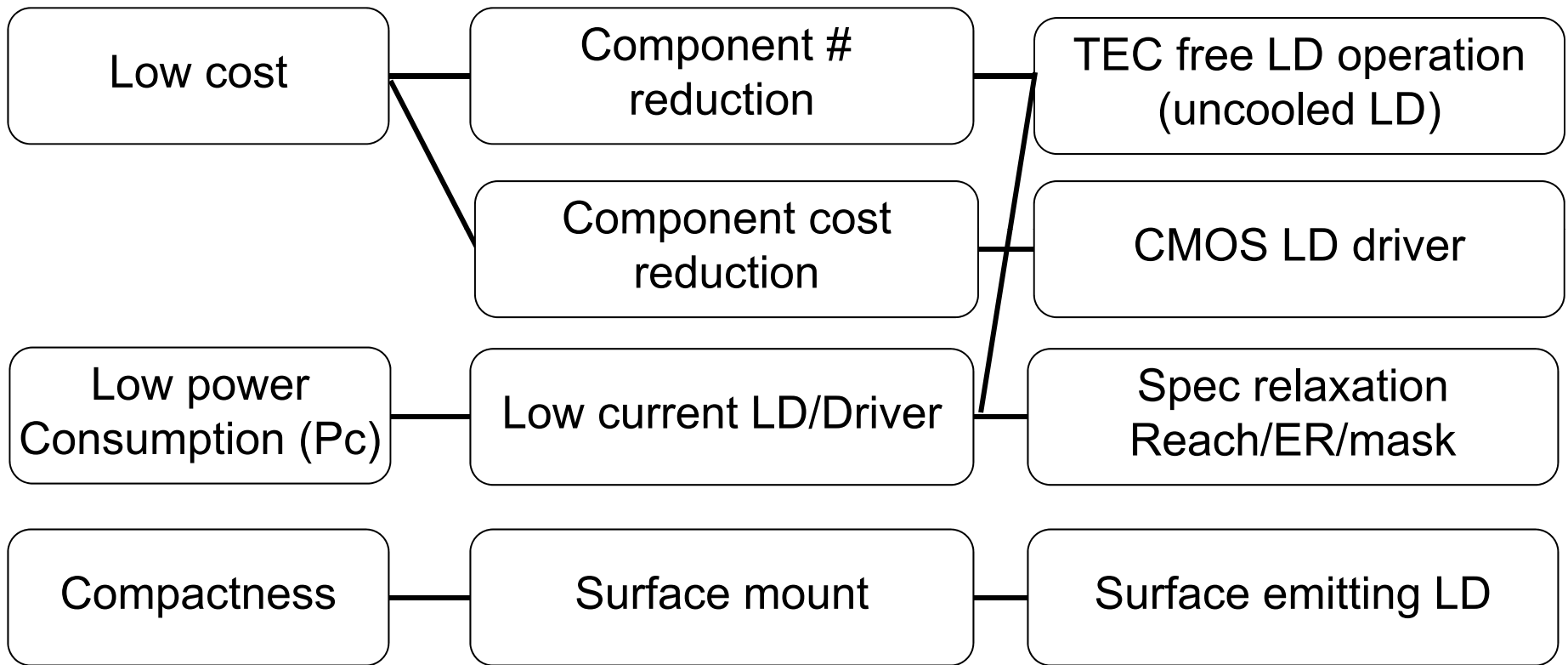
Standard	Fiber	MUX	2011	2012	2013-	Comments
LR4 10km	SMF	WDM	CFP Cooled -EML	CFP2 Cooled -DML	CFP4 Cooled-DML	Density Cost
nR4 (1) ~2km?	SMF	WDM			CFP4 <b>Low power consumption (Pc) DML</b>	Data Center
nR4 (2) ~550m?	SMF	parallel			CFP4 <b>Surface emitting 1.3μm DML</b>	Data Center
SR4+ >300m?	MMF	parallel			CFP4 <b>Surface emitting 1.3μm DML</b>	Data Center New MMF
SR4 60~100m	MMF	parallel			CFP4 VCSEL 850nm +EDC	Data Center

# Objectives and Approaches

## Objectives

## Challenges

## Approaches



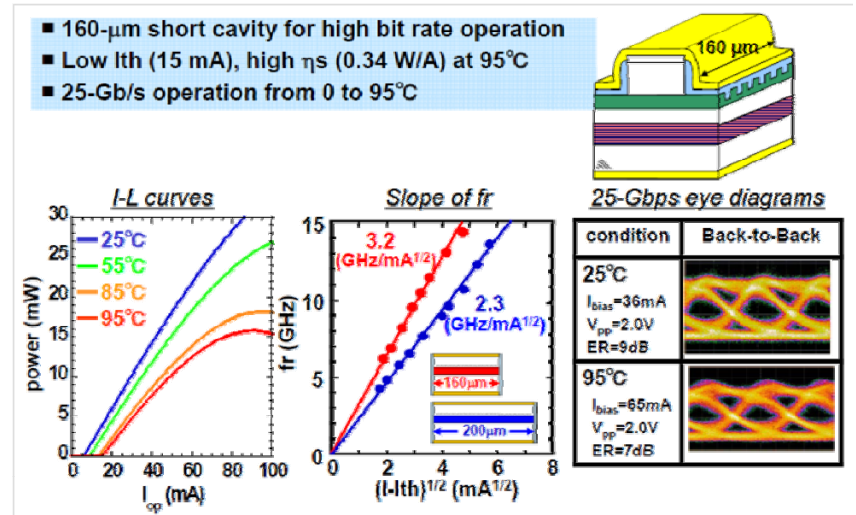
# nR4 Proposal

- Reduction of number of components is key to achieve the lowest cost solution for data center application.

Type	Fiber type	length	LD	Isolator	O-MUX deMUX	TEC	Opt. coupling
CFP	SMF	10 km	Cooled-EML	Req.	Req.	Req.	Active
CFP2/ CFP4	SMF	10 km	Cooled-DML	Req.	Req.	-	Active
<u>nR4 (WDM)</u>	SMF	2 km?	Low Pc integrated-DML	No ?	Req.	-	Active
nR4 (Parallel)	SMF	550m?	Surface emitting-DML	No ?	-	-	Active
SR4+ (Parallel)	New MMF	300m?	Surface emitting-DML	-	-	-	Passive
SR4 (Parallel)	MMF	100 m	VCSEL	EDC/ FEC	-	-	Passive

# Low Pc operation by TEC-free uncooled DML

- Low power consumption enabled by
  - ✓ **TEC-free 25-Gb/s Uncooled DML with CWDM grid using InGaAlAs-QW material system with Improved High-Temperature** keeping Static/Dynamic Performance
- Uncooled DML is most promising approach to enable 2.5W CFP4.



○ : Achievable with existing technology    × : Not feasible in near future

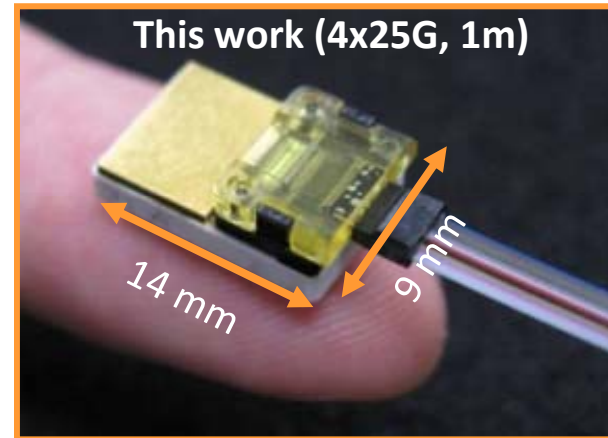
Ref: T. Fukamachi et. al., ECOC2009, 8.1.5, (2009)

Target application		EA		DML	
		Cooled	Uncooled	Cooled	Uncooled
CFP2	8W	○	—	○	—
CFP4	4W	TLD=55°C Vmod=1V ILD=40mA	Vmod=1V ILD=50mA	New Driver TLD=55°C Ibias=60mA	New Driver Ibias=70mA
	3.5W	×	Vmod=1V ILD=40mA	New Driver TLD=55°C Ibias=50mA	New Driver Ibias=60mA
	2.5W	×	×	×	<b>New Driver Ibias=30mA</b>

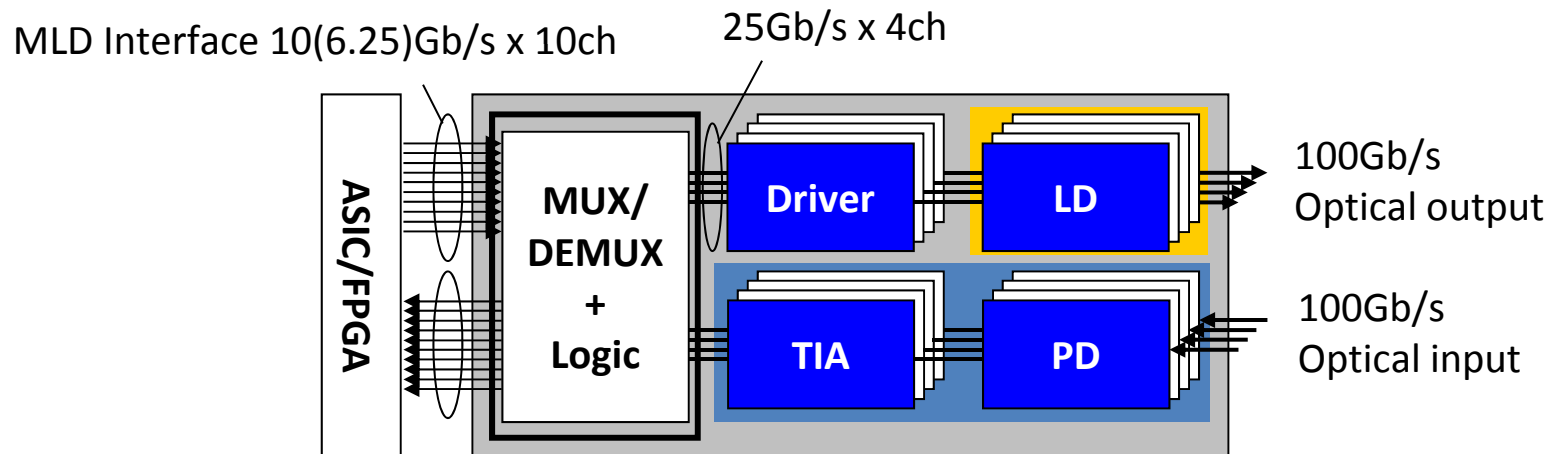
# Prototype 4 x 25G transceiver



Foot print: 144 x 78 mm<sup>2</sup>  
Power: 30W



This work (4x25G, 1m)  
Foot print : 14 x 9 mm<sup>2</sup> (1/100)  
Power: 2W (1/15)



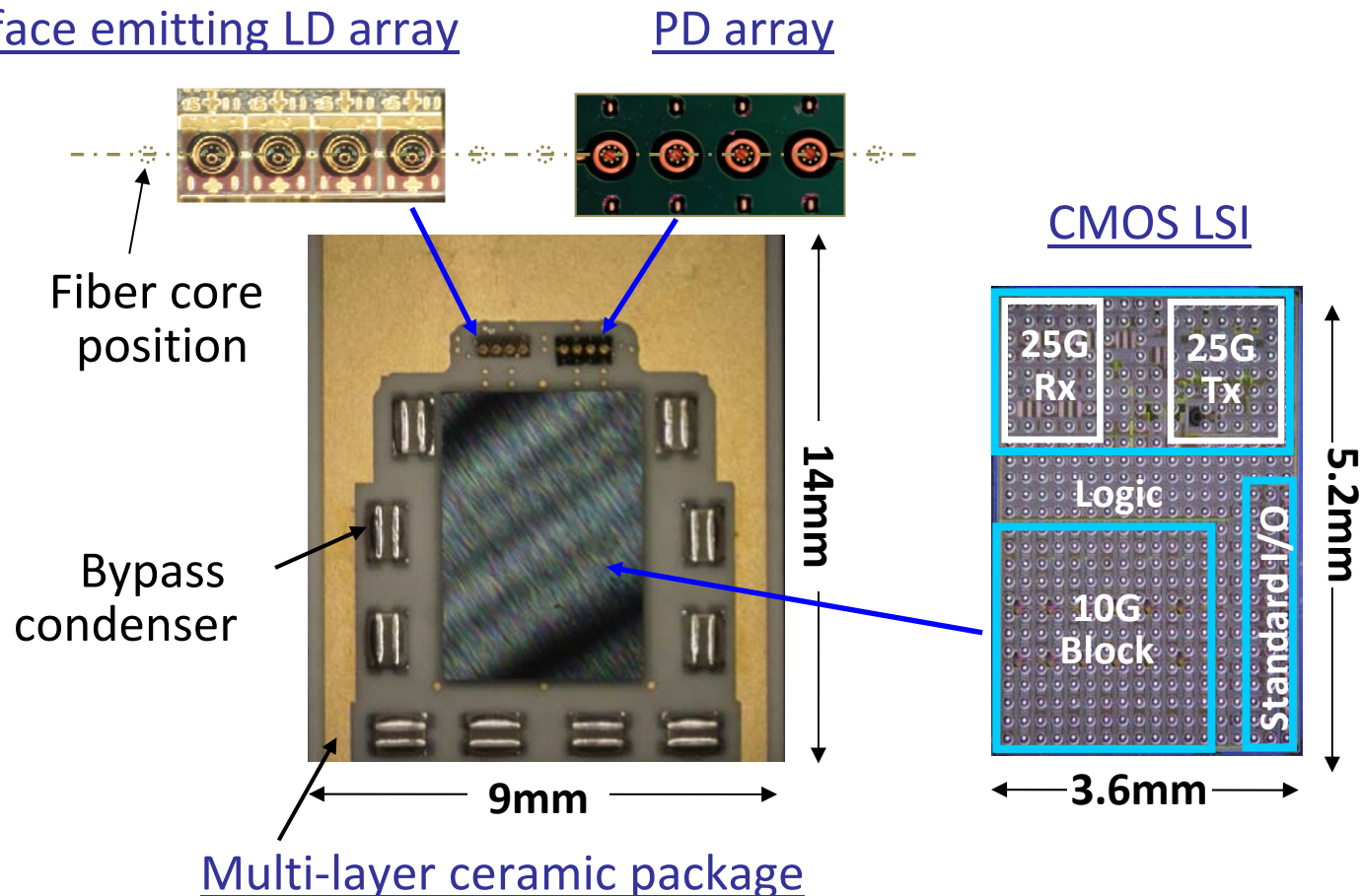
Ref: T. Takemoto et al., ECOC 2011, Th.12.B.5 (2011).  
A part of this work was performed under management of the PETRA supported by NEDO.

1 Nov 2011

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# Prototype 4 x 25G transceiver internal view

- Surface mount with passive alignment enables low cost module.



Ref: T. Takemoto et al., ECOC 2011, Th.12.B.5 (2011).

A part of this work was performed under management of the PETRA supported by NEDO.

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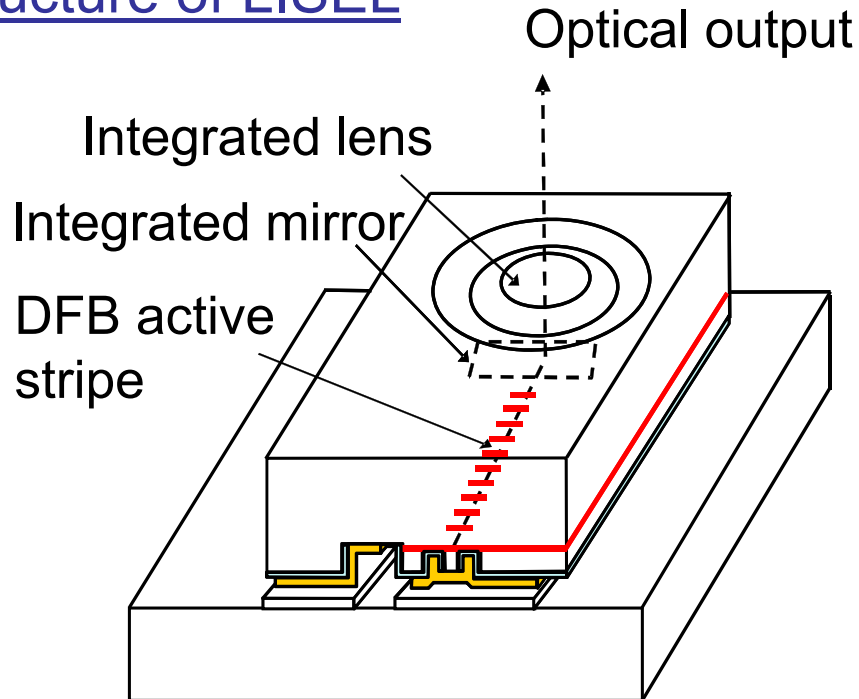
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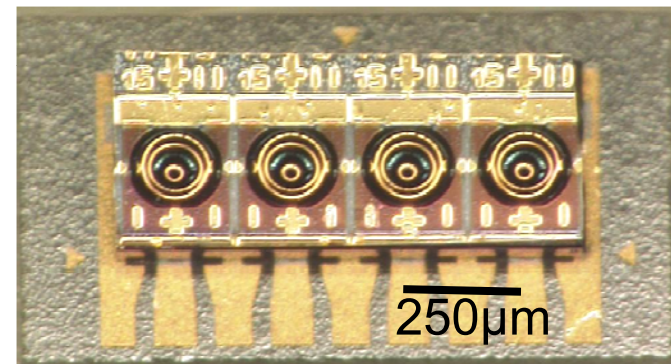
# Surface emitting DFB LD

- Lens Integrated Surface Emitting Laser (LISEL)
- 1.3 $\mu\text{m}$  operation with low  $I_{\text{th}}$  ( $\sim 15 \text{ mA}$  @85 $^{\circ}\text{C}$ )
- High speed (25Gb/s) up to 100  $^{\circ}\text{C}$
- Surface emitting/ Flip-chip mount

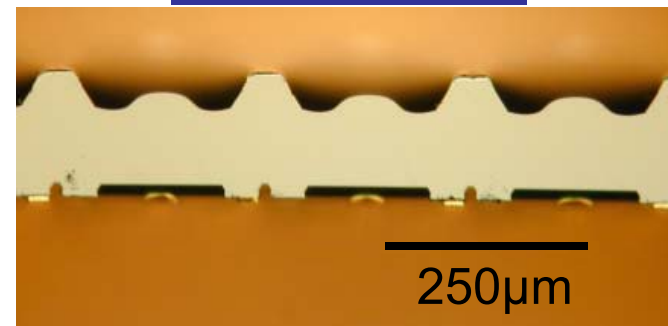
## Structure of LISEL



## 4ch-LISEL array



## Cross section



Ref: K. Adachi et al., J. Lightwave Tech. 29, 2899 (2011)

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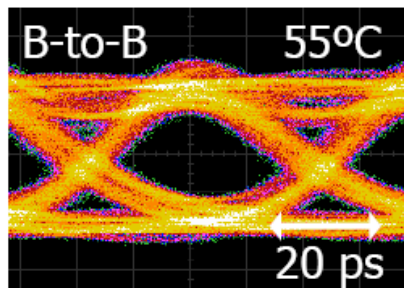
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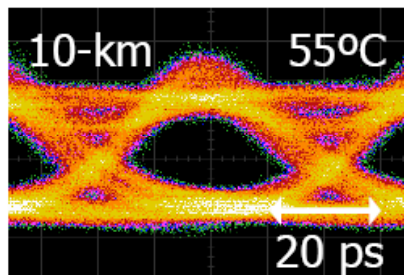
# Measurement of SMF transmission

- Four-wavelength 25-Gb/s 10-km error-free transmission (minimum received power: -11 dBm after 10-km SMF transmission)

## 25-Gb/s eye diagram



$I_{\text{bias}} = 50 \text{ mA}; I_{\text{mod}} = 33 \text{ mA}_{\text{pp}}$



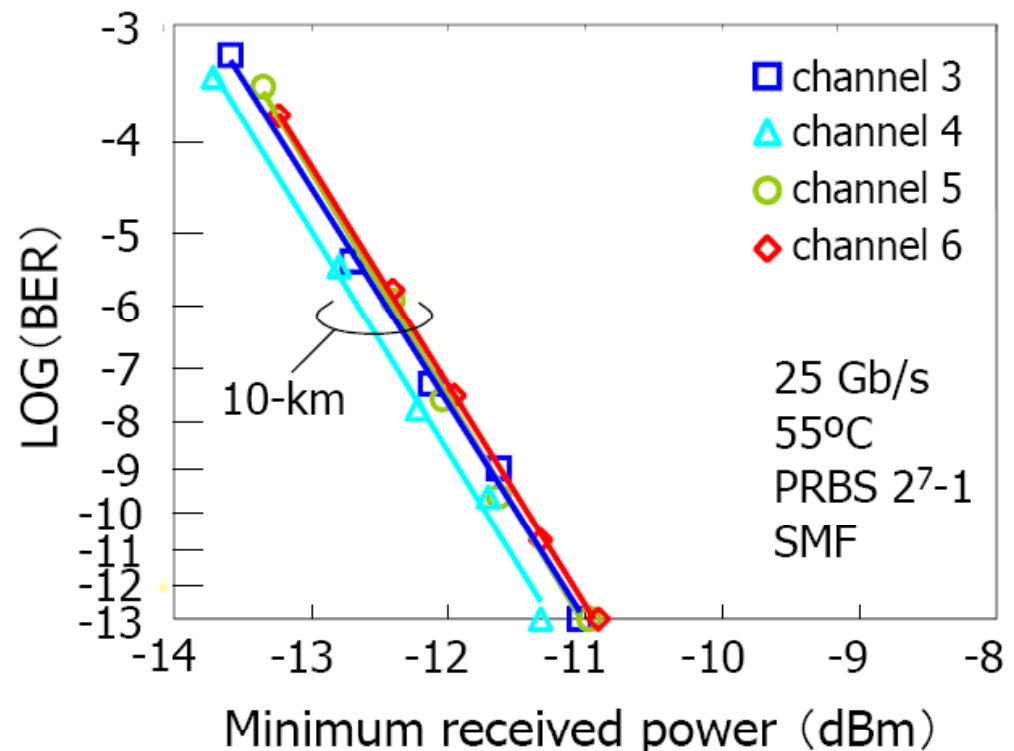
$I_{\text{bias}} = 55 \text{ mA}; I_{\text{mod}} = 33 \text{ mA}_{\text{pp}}$

Ref: K. Adachi et al., IPC 2011, TuD3 (2011).

*A part of this work was performed under management of the PETRA supported by NEDO.*

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## Bit-error-rate performance



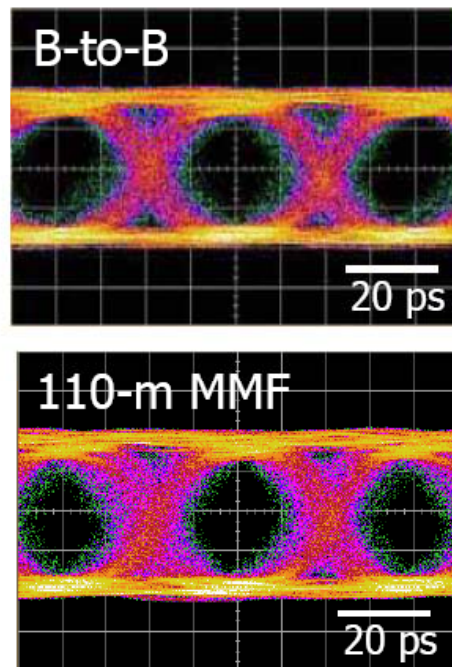
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# Measurement of MMF transmission

- 110-m MMF error-free transmission @ BER of  $10^{-12}$

25-Gb/s eye diagram



Used GI MMF : 1444 MHz·km @ 1.3  $\mu$ m

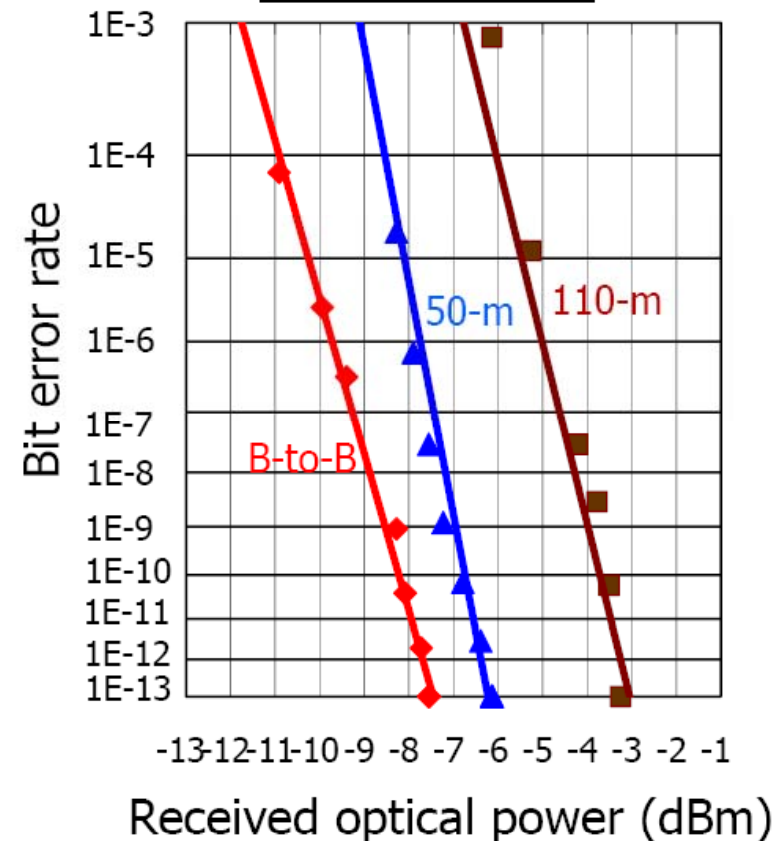
Ref: Y. Lee et al., ECOC 2011, We.10.P1.57 (2011)

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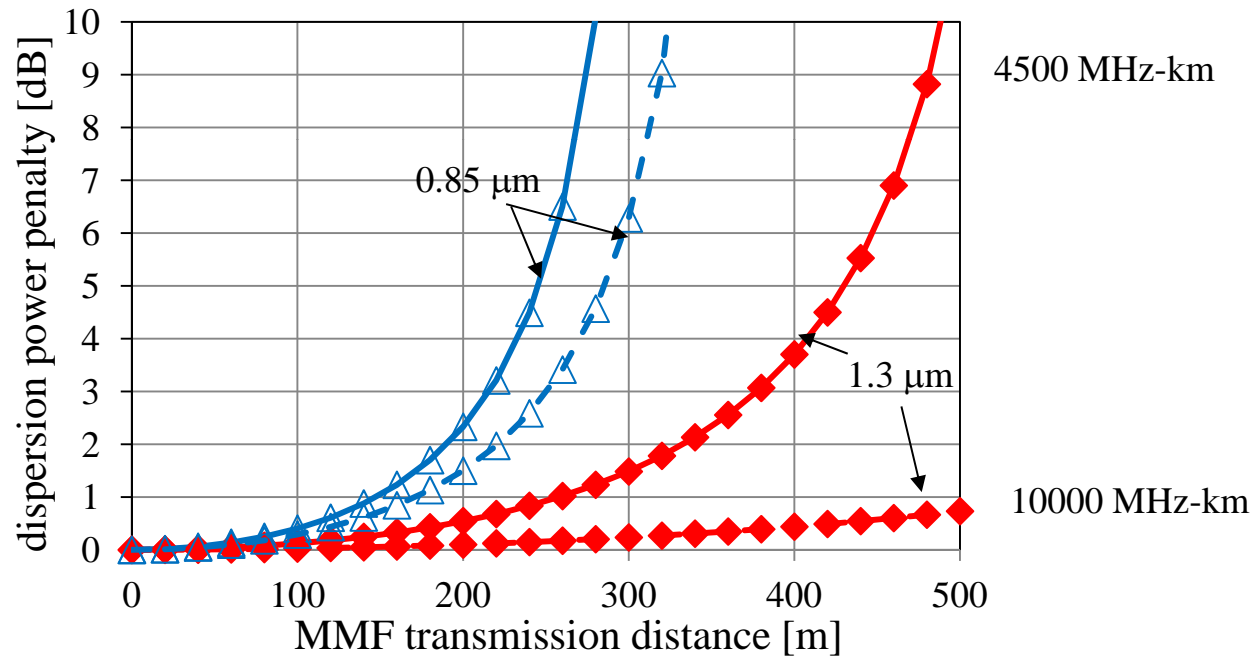
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Bit-error rate



# MMF Dispersion Penalty Improvement

Calculated dispersion power penalties for various MMFs with different modal bandwidths and for various wavelengths.



(\*) Solid lines: 4500MHz·km MMF, Dashed lines: 10000MHz·km MMF

Ref: Y. Lee et al., ECOC 2011, We.10.P1.57 (2011)

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# Relative Cost Analysis

Type	Fiber type	length	TOSA			LDD	O-MUX	Opt. coupling	Relative cost (TOSA+LDD+O-Mux)
			LD	Isolator	TEC				
CFP	SMF	10 km	Cooled EML	Req.	Req.	GaAs	Req.	Active	2.0
CFP2/ CFP4	SMF	10 km	Cooled-DML	Req.	Req.	SiGe	Req.	Active	1.0
<u>nR4 (WDM)</u>	<u>SMF</u>	<u>2 km?</u>	Low Pc integrate d-DML	<u>No ?</u>	<u>No</u>	<u>CMOS</u>	<u>Req.</u>	<u>Active</u>	<u>0.4</u>
nR4 (Parallel)	SMF	550m?	Surface emitting-DML	<u>No ?</u>	<u>No</u>	<u>CMOS</u>	No	Active	0.15
SR4+ (Parallel)	<b>New MMF</b>	300m?	Surface emitting-DML	<u>No</u>	<u>No</u>		<u>No</u>	Passive	<0.15
SR4 (Parallel)	MMF	100 m	4-VCSEL	<b>EDC</b>	<u>No</u>		<u>No</u>	Passive	

# Summary

- Technical feasibility of 1310nm optical device for short reach SMF (< 2 km) and extended reach MMF (< 300m OM4-like bandwidth) is demonstrated.
- Relative cost analysis indicates significant cost reduction in transmitter chain may be possible.
- Propose SG to study 1310nm optical device specifications in order to lower cost, power consumption and size of optical transceiver for nR4 application:
  1. Optical specification relaxation of 100GBASE-LR4; wavelength grid, ER, mask, etc.
  2. Feasibility of parallel SMF reaches beyond 550m.
  3. New MMF to achieve -300m reach using 1310nm surface emitting LD.

End of Contribution

Thanks!